

SURFACE MOUNT SUPER FAST RECOVERY DIODES

Features

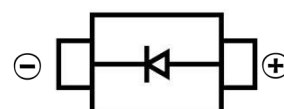
- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super-Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O



Mechanical Data

- Case: SMC/DO-214AB, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.21 grams (approx.)

SMC



Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	MURS305	MURS310	MURS315	MURS320	MURS330	MURS340	MURS360	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	100	150	200	300	400	600	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	105	140	210	280	420	V
Average Rectified Output Current @T _L = 75°C	I _O	3.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	100							A
Forward Voltage @I _F = 3.0A	V _{FM}	0.95				1.25		1.7	V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	5.0 500							μA
Reverse Recovery Time (Note 1)	t _{rr}	35							nS
Typical Junction Capacitance (Note 2)	C _j	45							pF
Typical Thermal Resistance (Note 3)	R _{θJL}	16							°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-65 to +150							°C

Note: 1. Measured with I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A. See figure 5.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.
3. Mounted on P.C. Board with 8.0mm² land area.

SURFACE MOUNT SUPER FAST RECOVERY DIODES

Typical Characteristics

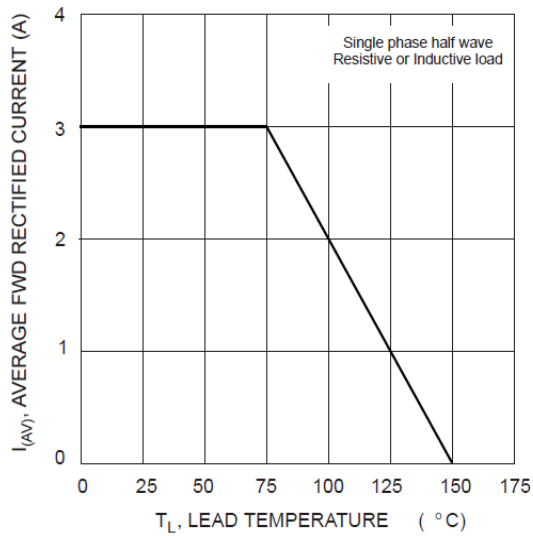


Fig. 1 Forward Current Derating Curve

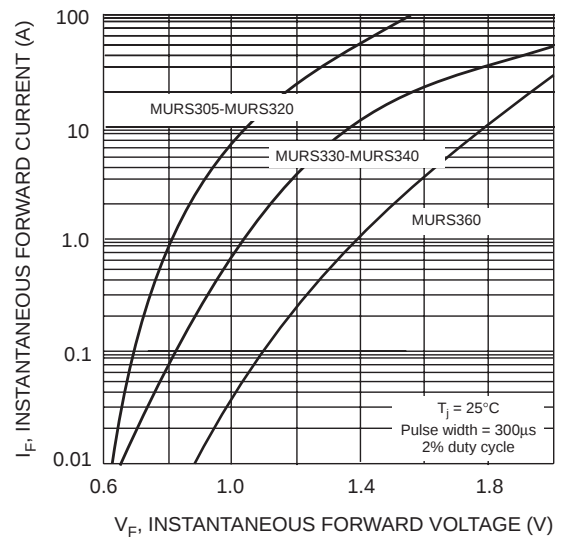


Fig. 2 Typical Forward Characteristics

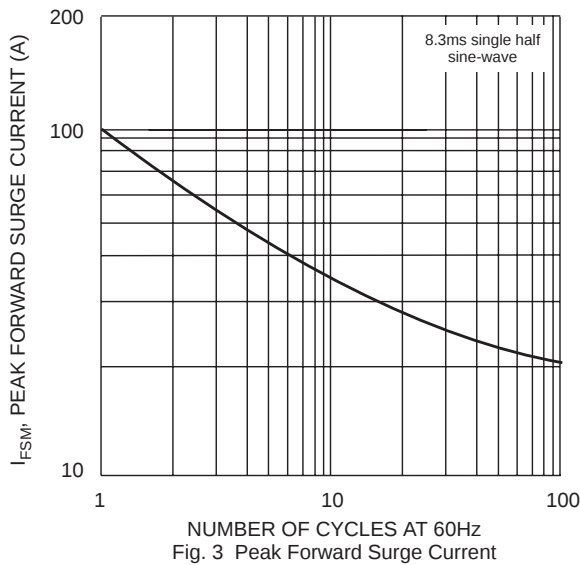


Fig. 3 Peak Forward Surge Current

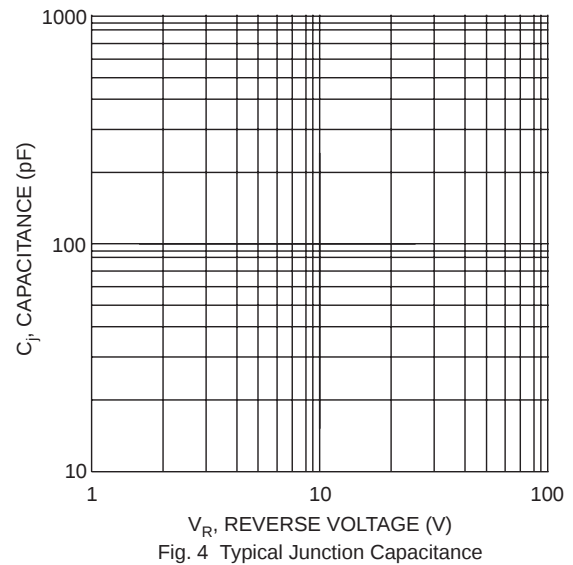
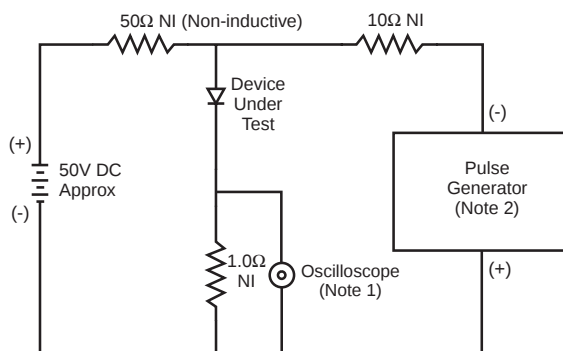
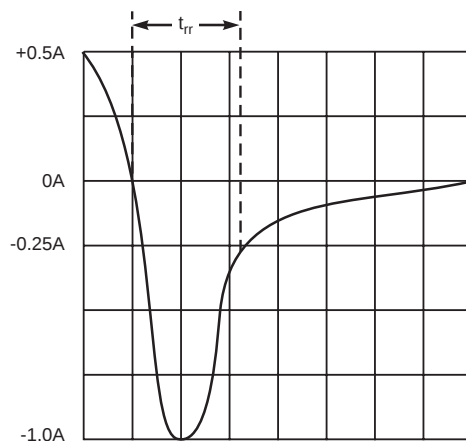


Fig. 4 Typical Junction Capacitance



Notes:

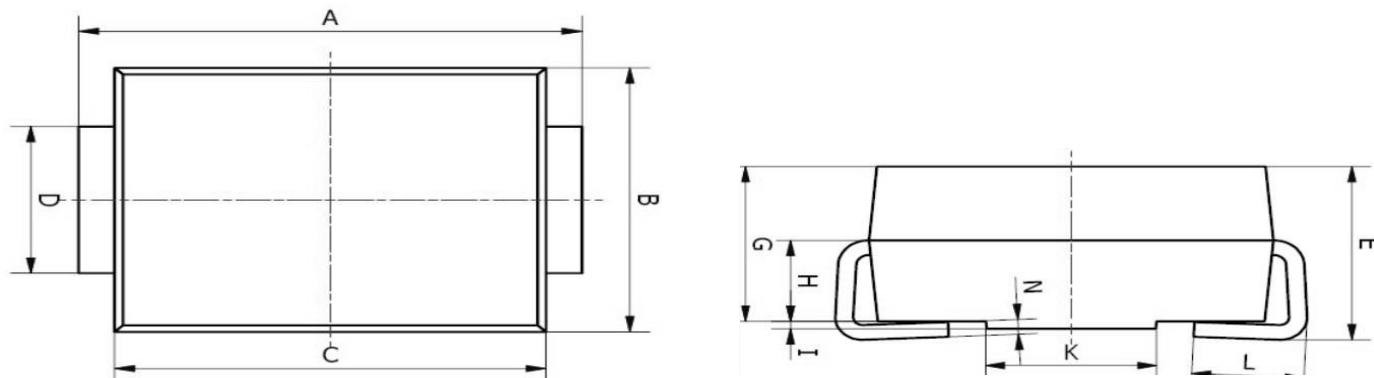
1. Rise Time = 7.0ns max. Input Impedance = 1.0M Ω , 22pF.
2. Rise Time = 10ns max. Input Impedance = 50 Ω .



Set time base for 5/10ns/cm

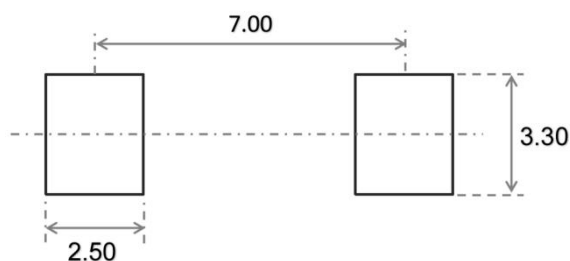
Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

SMC Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.75	8.13	0.305	0.320
B	5.59	6.22	0.220	0.245
C	6.60	7.11	0.260	0.280
D	2.75	3.25	0.108	0.128
E	2.25	2.82	0.089	0.111
G	2.00	2.62	0.079	0.103
H	1.26	1.56	0.050	0.061
I	0.05	0.15	0.002	0.006
K	4.30	6.00	0.169	0.236
L	1.25	1.75	0.049	0.069
N	0.10	0.30	0.004	0.012

SMC Suggested Pad Layout

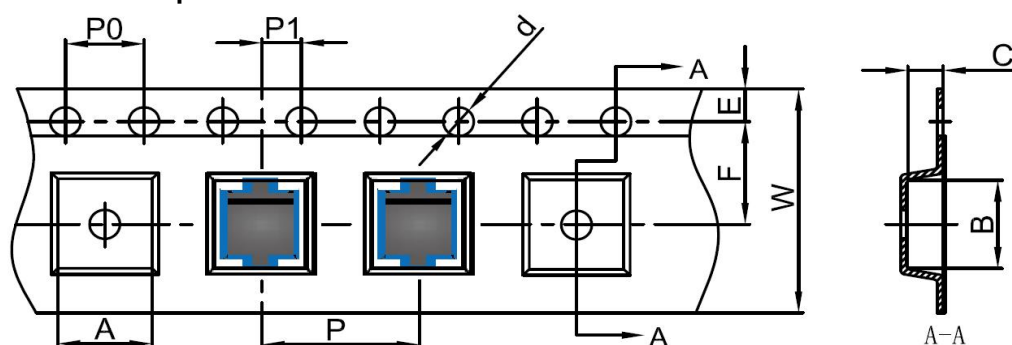


Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

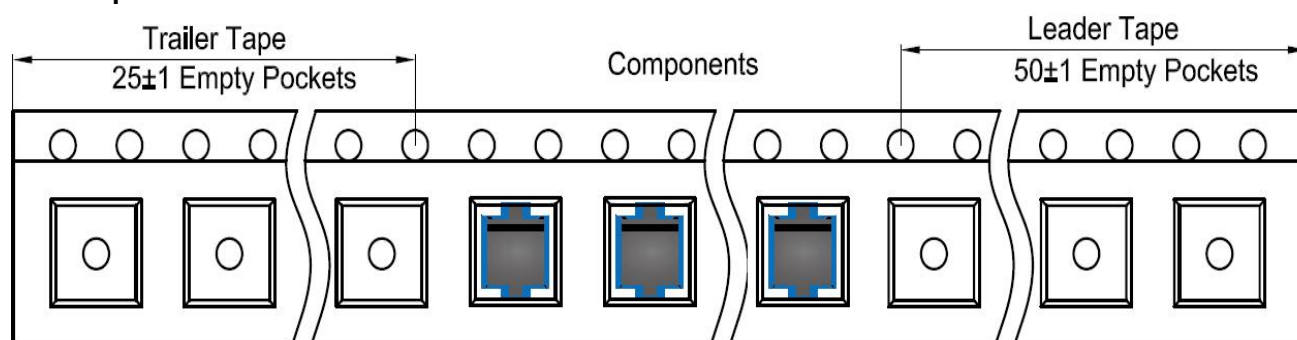
SMC Tape and Reel

SMC Embossed Carrier Tape

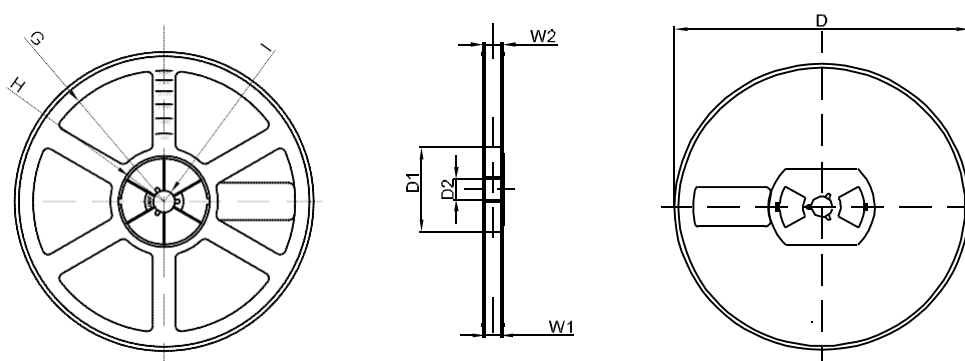


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SMC	6.3	8.25	2.90	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SMC Tape Leader and Trailer



SMC Reel



DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330	100	21	R165	R50	R6.50	16.4	21.00
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1